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148<sup>th</sup> Annual Meeting & Exhibition

# CALL FOR ABSTRACTS

March 10–14, 2019  
San Antonio, Texas, USA

## SUBMIT AN ABSTRACT TO:

### ELECTRONIC MATERIALS

### Phase Stability, Phase Transformations, and Reactive Phase Formation in Electronic Materials XVIII

This is the 18th in a series of TMS symposia addressing the stability, transformation, and formation of phases during the fabrication, processing, and utilization of electronic materials and devices. Topics of interest range from microelectronic technologies to advanced energy technologies, including phase stability, transformation, formation, and morphological evolution of electronic packaging materials, interconnection materials, integrated circuit materials, optoelectronic materials as well as energy storage and generating materials.

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